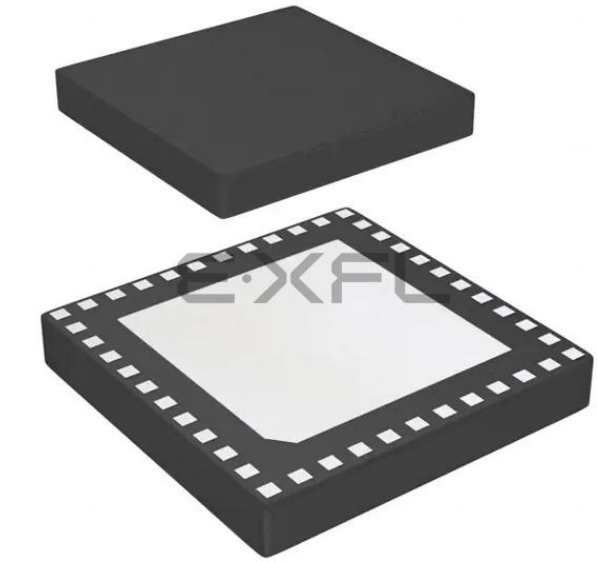

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx270f256d-v-tl

TABLE 4: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN SOIC, SPDIP, SSOP (TOP VIEW)(1,2,3)

PIC32MX210F016B
PIC32MX220F032B
PIC32MX230F064B
PIC32MX230F256B
PIC32MX250F128B
PIC32MX270F256B

Pin #	Full Pin Name	Pin #	Full Pin Name
1	$\overline{MCLR}$	15	V_{BUS}
2	PGED3/V_{REF}+/CV_{REF}+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	16	TDI/RPB7/CTED3/PMD5/INT0/RB7
3	PGEC3/V_{REF}-/CV_{REF}-/AN1/RPA1/CTED2/PMD6/RA1	17	TCK/RPB8/SCL1/CTED10/PMD4/RB8
4	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	18	TDO/RPB9/SDA1/CTED4/PMD3/RB9
5	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	19	V_{SS}
6	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	20	V_{CAP}
7	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	21	PGED2/RPB10/D+/CTED11/RB10
8	V_{SS}	22	PGEC2/RPB11/D-/RB11
9	OSC1/CLKI/RPA2/RA2	23	V_{USB3V3}
10	OSC2/CLKO/RPA3/PMA0/RA3	24	AN11/RPB13/CTPLS/PMRD/RB13
11	SOSCI/RPB4/RB4	25	CV_{REFOUT}/AN10/C3INB/RPB14/V_{BUSON}/SCK1/CTED5/RB14
12	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
13	V_{DD}	27	AV_{SS}
14	TMS/RPB5/USBID/RB5	28	AV_{DD}

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and Section 11.3 “Peripheral Pin Select” for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See Section 11.0 “I/O Ports” for more information.

3: Shaded pins are 5V tolerant.

4.0 MEMORY ORGANIZATION

Note:	This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source.For detailed information, refer to Section 3. “Memory Organization” (DS60001115), which is available from the Documentation > Reference Manual section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers provide 4 GB unified virtual memory address space. All memory regions, including program, data memory, Special Function Registers (SFRs), and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX 28/36/44-pin Family devices to execute from data memory.

Key features include:

- 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/KSEG1) mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable (KSEG0) and non-cacheable (KSEG1) address regions

4.1 PIC32MX1XX/2XX 28/36/44-pin Family Memory Layout

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX 28/36/44-pin Family devices are illustrated in Figure 4-1 through Figure 4-6.

Table 4-1 provides SFR memory map details.

REGISTER 8-4: REFOTRIM: REFERENCE OSCILLATOR TRIM REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ROTRIM<8:1>							
23:16	R/W-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	ROTRIM<0>	—	—	—	—	—	—	—
15:8	U-0	R-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-23 ROTRIM<8:0>: Reference Oscillator Trim bits

111111111 = 511/512 divisor added to RODIV value
111111110 = 510/512 divisor added to RODIV value
•
•
•
100000000 = 256/512 divisor added to RODIV value
•
•
•
000000010 = 2/512 divisor added to RODIV value
000000001 = 1/512 divisor added to RODIV value
000000000 = 0/512 divisor added to RODIV value

bit 22-0 Unimplemented: Read as ‘0’

Note:	While the ON (REFOCON<15>) bit is ‘1’, writes to this register do not take effect until the DIVSWEN bit is also set to ‘1’.

REGISTER 9-1: DMACON: DMA CO NTROLLER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
	ON(1)	—	—	SUSPEND	DMABUSY	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-16 Unimplemented: Read as ‘0’

bit 15 ON: DMA On bit(1)
1 = DMA module is enabled
0 = DMA module is disabled

bit 14-13 Unimplemented: Read as ‘0’

bit 12 SUSPEND: DMA Suspend bit
1 = DMA transfers are suspended to allow CPU uninterrupted access to data bus
0 = DMA operates normally

bit 11 DMABUSY: DMA Module Busy bit
1 = DMA module is active
0 = DMA module is disabled and not actively transferring data

bit 10-0 Unimplemented: Read as ‘0’

Note 1: When using 1:1 PBCLK divisor, the user’s software should not read/write the peripheral’s SFRs in the SYSCLK cycle immediately following the instruction that clears the module’s ON bit.

REGISTER 9-10: DCHxSSA: DMA CHANNEL 'x' SOURCE START ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 CHSSA<31:0> Channel Source Start Address bits
Channel source start address.
Note: This must be the physical address of the source.

REGISTER 9-11: DCHxDSA: DMA CHANNEL 'x ' DESTINATION START ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSA<31:24>							
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSA<23:16>							
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSA<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSA<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-0 CHDSA<31:0>: Channel Destination Start Address bits
Channel destination start address.
Note: This must be the physical address of the destination.

REGISTER 10-3: U1OTGSTAT: USB OTG STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R-0	U-0	R-0	U-0	R-0	R-0	U-0	R-0
	ID	—	LSTATE	—	SESVD	SESEND	—	VBUSVD

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-8 Unimplemented: Read as ‘0’

bit 7 ID: ID Pin State Indicator bit
1 = No cable is attached or a “type B” cable has been inserted into the USB receptacle
0 = A “type A” OTG cable has been inserted into the USB receptacle

bit 6 Unimplemented: Read as ‘0’

bit 5 LSTATE: Line State Stable Indicator bit
1 = USB line state (SE0 (U1CON<6>) bit and JSTATE (U1CON<7>)) bit has been stable for previous 1 ms
0 = USB line state (SE0 and JSTATE) has not been stable for previous 1 ms

bit 4 Unimplemented: Read as ‘0’

bit 3 SESVD: Session Valid Indicator bit
1 = VBUS voltage is above Session Valid on the A or B device
0 = VBUS voltage is below Session Valid on the A or B device

bit 2 SESEND: B-Device Session End Indicator bit
1 = VBUS voltage is below Session Valid on the B device
0 = VBUS voltage is above Session Valid on the B device

bit 1 Unimplemented: Read as ‘0’

bit 0 VBUSVD: A-Device VBUS Valid Indicator bit
1 = VBUS voltage is above Session Valid on the A device
0 = VBUS voltage is below Session Valid on the A device

REGISTER 14-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	ON(1,2)	—	—	—	—	—	—	—
7:0	U-0	R-y	R-y	R-y	R-y	R-y	R/W-0	R/W-0
	—	SWDTPS<4:0>					WDTWINEN	WDTCLR

Legend:	y = Values set from Configuration bits on POR		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 Unimplemented: Read as '0'

bit 15 ON: Watchdog Timer Enable bit(1,2)
1 = Enables the WDT if it is not enabled by the device configuration
0 = Disable the WDT if it was enabled in software

bit 14-7 Unimplemented: Read as '0'

bit 6-2 SWDTPS<4:0>: Shadow Copy of Watchdog Timer Postscaler Value from Device Configuration bits
On reset, these bits are set to the values of the WDTPS <4:0> of Configuration bits.

bit 1 WDTWINEN: Watchdog Timer Window Enable bit
1 = Enable windowed Watchdog Timer
0 = Disable windowed Watchdog Timer

bit 0 WDTCLR: Watchdog Timer Reset bit
1 = Writing a '1' will clear the WDT
0 = Software cannot force this bit to a '0'

Note 1: A read of this bit results in a '1' if the Watchdog Timer is enabled by the device configuration or software.
2: When using the 1:1 PBCLK divisor, the user's software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 20-4: PMAEN: PARALLEL PORT PIN ENABLE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	PTEN14	—	—	—	PTEN<10:8>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	PTEN<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-15 Unimplemented: Read as '0'

bit 15-14 PTEN14: PMCS1 Address Port Enable bits
1 = PMA14 functions as either PMA14 or PMCS1(1)
0 = PMA14 functions as port I/O

bit 13-11 Unimplemented: Read as '0'

bit 10-2 PTEN<10:2>: PMP Address Port Enable bits
1 = PMA<10:2> function as PMP address lines
0 = PMA<10:2> function as port I/O

bit 1-0 PTEN<1:0>: PMALH/PMALL Address Port Enable bits
1 = PMA1 and PMA0 function as either PMA<1:0> or PMALH and PMALL(2)
0 = PMA1 and PMA0 pads functions as port I/O

Note 1: The use of this pin as PMA14 or CS1 is selected by the CSF<1:0> bits in the PMCON register.

2: The use of these pins as PMA1/PMA0 or PMALH/PMALL depends on the Address/Data Multiplex mode selected by bits ADRMUX<1:0> in the PMCON register.

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 ARPT<7:0>: Alarm Repeat Counter Value bits(2)

11111111 = Alarm will trigger 256 times

•
•
•

00000000 = Alarm will trigger one time

The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

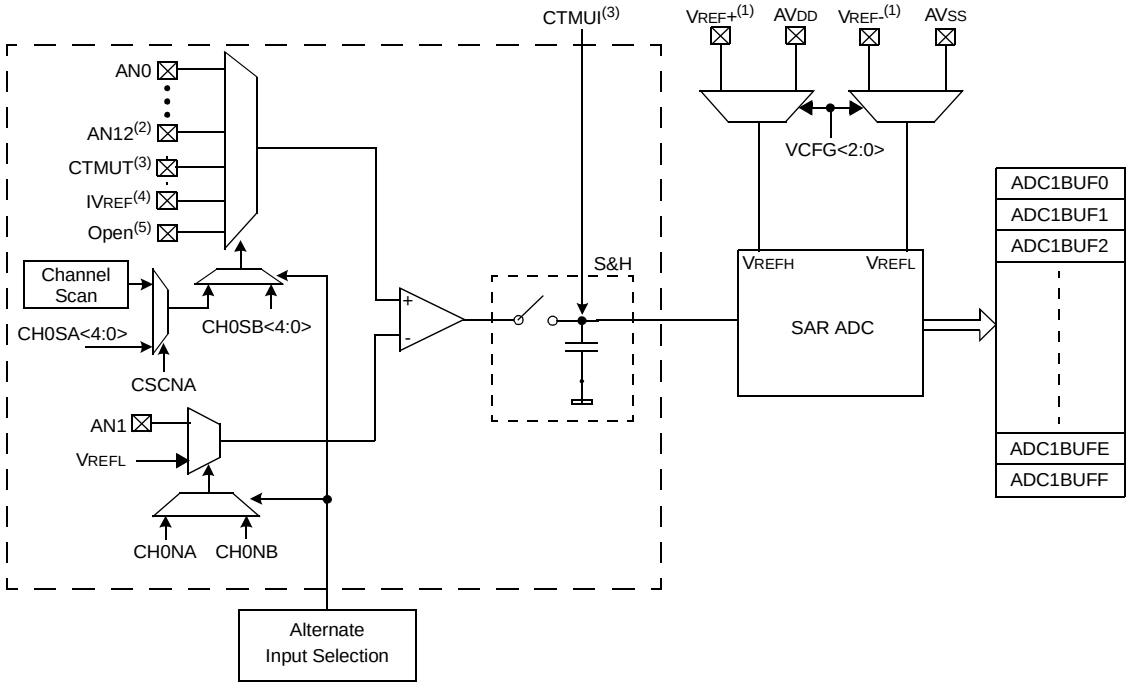
> Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 17. “10-bit Analog-to-Digital Converter (ADC)” (DS60001104), which is available from the Documentation > Reference Manual section of the Microchip PIC32 web site (www.microchip.com/pic32).

The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed
- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

A block diagram of the 10-bit ADC is illustrated in Figure 22-1. Figure 22-2 illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



Note 1: VREF+ and VREF- inputs can be multiplexed with other analog inputs.

2: AN8 is only available on 44-pin devices. AN6, AN7, and AN12 are not available on 28-pin devices.

3: Connected to the CTMU module. See Section 25.0 “Charge Time Measurement Unit (CTMU)” for more information.

4: Internal precision voltage reference (1.2V).

5: This selection is only used with CTMU capacitive and time measurement.

The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a POSC of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from POSC to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to POSC, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a WAIT instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

27.2 Configuration Registers

TABLE 27-1: DEVCFG: DEVICE CONFIGURATION WORD SUMMARY

Virtual Address (BFC0_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
0BF0	DEVCFG3	31:16	FVBUSONIO	FUSBIDIO	IOL1WAY	PMDL1WAY	—	—	—	—	—	—	—	—	—	—	—	—	xxxx
		15:0	USERID<15:0>																xxxx
0BF4	DEVCFG2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	FPLLODIV<2:0>			xxxx
		15:0	UPLLEN(1)	—	—	—	—	UPLLIDIV<2:0>(1)			—	FPLLMUL<2:0>			—	FPLLIDIV<2:0>			xxxx
0BF8	DEVCFG1	31:16	—	—	—	—	—	—	FWDTWINSZ<1:0>		FWDTEN	WINDIS	—	WDTPS<4:0>					xxxx
		15:0	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>		IESO	—	FSOSCEN	—	—	FNOSC<2:0>			xxxx
0BFC	DEVCFG0	31:16	—	—	—	CP	—	—	—	BWP	—	—	—	—	—	PWP<8:6>(2)			xxxx
		15:0	PWP<5:0>						—	—	—	—	—	ICESEL<1:0>		JTAGEN	DEBUG<1:0>		xxxx

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: This bit is only available on PIC32MX2XX devices.
2: PWP<8:7> are only available on devices with 256 KB of Flash.

TABLE 27-2: DEVICE ID, REVISION, AND CONFIGURATION SUMMARY

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets (1)
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F220	DEVID	31:16	VER<3:0>				DEVID<27:16>												xxxx (1)
		15:0	DEVID<15:0>																xxxx (1)
F200	CFGCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	IOLOCK	PMDLOCK	—	—	—	—	—	—	—	—	JTAGEN	—	—	TDOEN	000B
F230	SYSKEY(3)	31:16	SYSKEY<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.
Note 1: Reset values are dependent on the device variant.

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 PWP<8:0>: Program Flash Write-Protect bits(3)

Prevents selected program Flash memory pages from being modified during code execution.
111111111 = Disabled
111111110 = Memory below 0x0400 address is write-protected
111111101 = Memory below 0x0800 address is write-protected
111111100 = Memory below 0x0C00 address is write-protected
111111011 = Memory below 0x1000 (4K) address is write-protected
111111010 = Memory below 0x1400 address is write-protected
111111001 = Memory below 0x1800 address is write-protected
111111000 = Memory below 0x1C00 address is write-protected
111110111 = Memory below 0x2000 (8K) address is write-protected
111110110 = Memory below 0x2400 address is write-protected
111110101 = Memory below 0x2800 address is write-protected
111110100 = Memory below 0x2C00 address is write-protected
111110011 = Memory below 0x3000 address is write-protected
111110010 = Memory below 0x3400 address is write-protected
111110001 = Memory below 0x3800 address is write-protected
111110000 = Memory below 0x3C00 address is write-protected
111101111 = Memory below 0x4000 (16K) address is write-protected
•
•
•
110111111 = Memory below 0x10000 (64K) address is write-protected
•
•
•
101111111 = Memory below 0x20000 (128K) address is write-protected
•
•
•
011111111 = Memory below 0x40000 (256K) address is write-protected
•
•
•
000000000 = All possible memory is write-protected

bit 9-5 Reserved: Write ‘1’

bit 4-3 ICESEL<1:0>: In-Circuit Emulator/Debugger Communication Channel Select bits(2)
11 = PGEC1/PGED1 pair is used
10 = PGEC2/PGED2 pair is used
01 = PGEC3/PGED3 pair is used
00 = PGEC4/PGED4 pair is used(2)

bit 2 JTAGEN: JTAG Enable bit(1)
1 = JTAG is enabled
0 = JTAG is disabled

bit 1-0 DEBUG<1:0>: Background Debugger Enable bits (forced to ‘11’ if code-protect is enabled)
1x = Debugger is disabled
0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.
2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the “Pin Diagrams” section for availability.
3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts) (1)	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX 28/36/44-pin Family
DC5	2.3-3.6V	-40°C to +85°C	40 MHz
DC5b	2.3-3.6V	-40°C to +105°C	40 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S (({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/ ΘJA			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 28-pin SSOP	ΘJA	71	—	°C/W	1
Package Thermal Resistance, 28-pin SOIC	ΘJA	50	—	°C/W	1
Package Thermal Resistance, 28-pin SPDIP	ΘJA	42	—	°C/W	1
Package Thermal Resistance, 28-pin QFN	ΘJA	35	—	°C/W	1
Package Thermal Resistance, 36-pin VTLA	ΘJA	31	—	°C/W	1
Package Thermal Resistance, 44-pin QFN	ΘJA	32	—	°C/W	1
Package Thermal Resistance, 44-pin TQFP	ΘJA	45	—	°C/W	1
Package Thermal Resistance, 44-pin VTLA	ΘJA	30	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (ΘJA) numbers are achieved by package simulations.

TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C dTA d+85°C for Industrial -40°C dTA d+105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typ. (1)	Max.	Units	Conditions
DI60a	IICL	Input Low Injection Current	0	—	-5(2,5)	mA	This parameter applies to all pins, with the exception of the power pins.
DI60b	IICH	Input High Injection Current	0	—	+5(3,4,5)	mA	This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSCI, SOSCO, OSC1, D+, and D- pins.
DI60c	¦IICT	Total Input Injection Current (sum of all I/O and Control pins)	-20(6)	—	+20(6)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) d ¦IICT)

Note 1: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: VIL source < (VSS - 0.3). Characterized but not tested.

3: VIH source > (VDD + 0.3) for non-5V tolerant pins only.

4: Digital 5V tolerant pins do not have an internal high side diode to VDD, and therefore, cannot tolerate any “positive” input injection current.

5: Injection currents > | 0 | can affect the ADC results by approximately 4 to 6 counts (i.e., VIH Source > (VDD + 0.3) or VIL source < (VSS - 0.3)).

6: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. If Note 2, IICL = (((Vss - 0.3) - VIL source) / Rs). If Note 3, IICH = ((IICH source - (VDD + 0.3)) / RS). RS = Resistance between input source voltage and device pin. If (VSS - 0.3) dVSOURCE d(VDD + 0.3), injection current = 0.

TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C dTA d+85°C for Industrial -40°C dTA d+105°C for V-temp				
Param. No.	Symbol	Characteristics	Min.	Typical (1)	Max.	Units	Conditions
		Program Flash Memory (3)					
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See Note 4
D136	TRW	Row Write Cycle Time	—	6675	—		See Note 2,4
D137	TPE	Page Erase Cycle Time	—	20011	—		See Note 4
	TCE	Chip Erase Cycle Time	—	80180	—		See Note 4

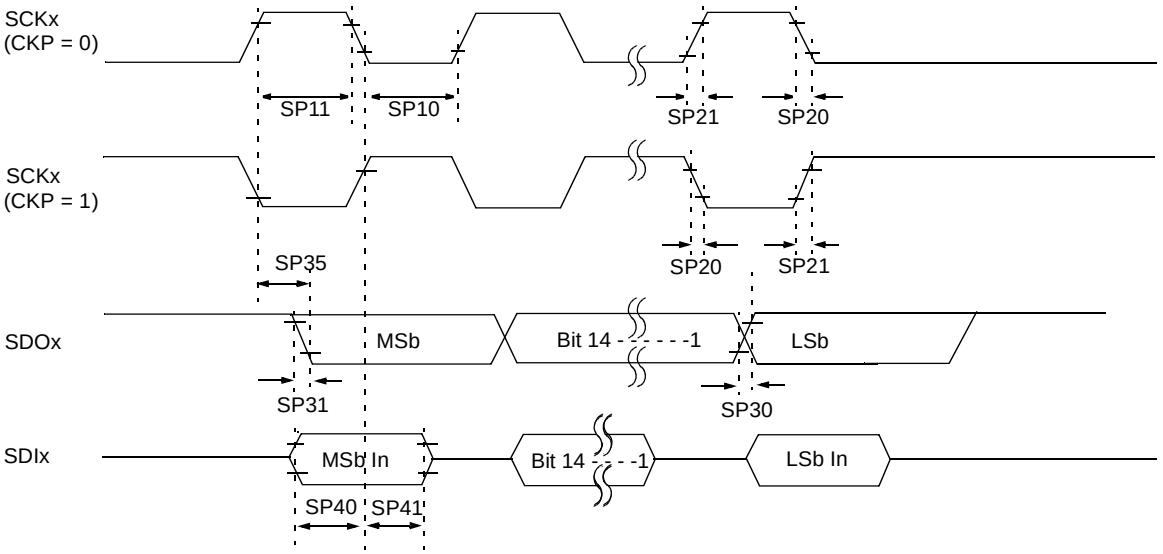
Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the “PIC32 Flash Programming Specification” (DS60001145) for operating conditions during programming and erase cycles.

4: This parameter depends on FRC accuracy (See Table 30-19) and FRC tuning values (See Register 8-2).

FIGURE 30-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C dTA d+85°C for Industrial -40°C dTA d+105°C for V-temp				
Param. No.	Symbol	Characteristics (1)	Min.	Typical (2)	Max.	Units	Conditions
SP10	TscL	SCKx Output Low Time (Note 3)	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time (Note 3)	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time (Note 4)	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time (Note 4)	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time (Note 4)	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time (Note 4)	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.